Unit: mm

TOSHIBA LED Lamps

TLRF1060(T18),TLSF1060(T18),TLOF1060(T18) TLYF1060(T18),TLPYF1060(T18),TLGF1060(T18) TLFGF1060(T18),TLPGF1060(T18)

Panel Circuit Indicators

TLYF1060

TLPYF1060

TLGF1060

TLFGF1060

TLPGF1060

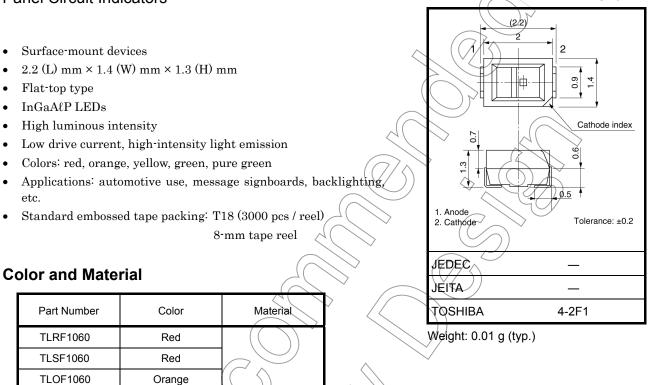
Yellow

Yellow

Green

Gréen

Pure Green



InGaAlP

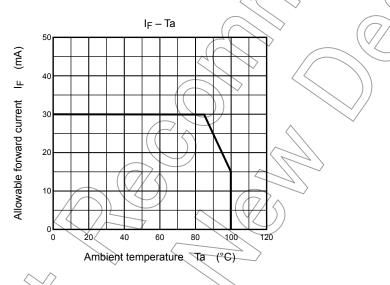
Absolute Maximum Ratings (Ta = 25°C)

Part Number	Forward Current I _F (mA) Please see Note 1	Reverse Voltage V _R (V)	Power Dissipation P _D (mW)	Operation Temperature T _{opr} (°C)	Storage Temperature T _{stg} (°C)
TLRF1060					
TLSF1060					
TLOF1060					
TLYF1060	30	15	75	-40 to 100	-40 to 100
TLPYF1060		10	15		
TLGF1060				$\overline{\Box}$	
TLFGF1060			\langle	$\langle \vee \rangle$	
TLPGF1060			(

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Forward current derating



Electrical Characteristics (Ta = 25°C)

Part Number	Forward Voltage V _F				Reverse Current I _R		
Fait Number	Min	Тур.	Max	7	Max	V _R	
TLRF1060	1.7	(2.0)	2.5)			
TLSF1060	1.7	2.0	2.5				
TLOF1060	1.7	2.0	2.5				
TLYF1060	1.7	2.1	2.5	20	10	15	
TLPYF1060	1.7	2.1	2.5	20	10	15	
TLGF1060	1.7	2.1	2.5				
TLFGF1060	1.7	2.1	2.5				
TLPGF1060	1.7	2.1	2.5				
Unit		V		mA	μA	V	

Optical Characteristics-1 (Ta = 25°C)

Part Number	Luminous Intensity IV				Available Iv rank
Fait Number	Min	Тур.	Max	١ _F	Please see Note 2
TLRF1060	40	100	320	20	PA / QA / RA / SA
TLSF1060	100	200	500	20	RA / SA / TA
TLOF1060	100	220	500	20	RA / SA / TA
TLYF1060	63	180	320	20	QA / RA / SA
TLPYF1060	40	100	320	20	PA / QA / RA / SA
TLGF1060	40	80	320	20	PA / QA / RA / SA
TLFGF1060	25	50	125	20	NA / PA / QA
TLPGF1060	10	20	50	20	LA / MA / NA
Unit	mcd		mA		

Note 2: The specification on the above table is used for Iv classification of LEDs in Toshiba facility. Each reel includes the same rank LEDs. Let the delivery ratio of each rank be unquestioned.

Rank	Luminous Intensity IV				
Nalik	Min	Max			
LA	10	20			
MA	16	32			
NA	25	50			
PA	40	80			
QA	63	125			
RA	100	200			
SA	160	320			
TA	250	500			
Unit	mcd	mca			

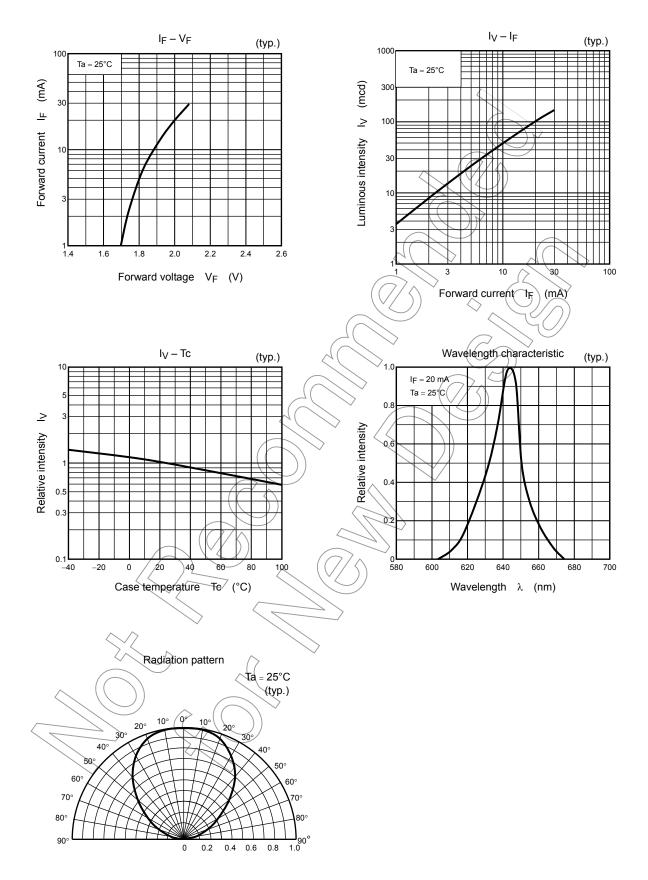
Optical Characteristics -2 (Ta = 25°C)

	Emission Spectrum							
Part Number	<pre></pre>	Reak Emission Wavelength λ_p					١F	
\sim	∧ ^{Min}	Тур.	Max	Тур.	Min	Тур.	Max	۲
TLRF1060		644		18	624	630	638	
TLSF1060		623	$\overline{\langle}$	17	607	613	621	
TŁOĘ1060	$) \rightarrow$	612		15	599	605	613	
TLYF1060		590		13	580	587	595	20
TLPYF1060		583		13	574	580	586	20
TLGE1060		574	/	11	565	571	576	
TLFGF1060		568	>	11	565	565	565	
TLPGF1060	_	562	_	11	555	558	564	
Unit		nm		nm		nm		mA

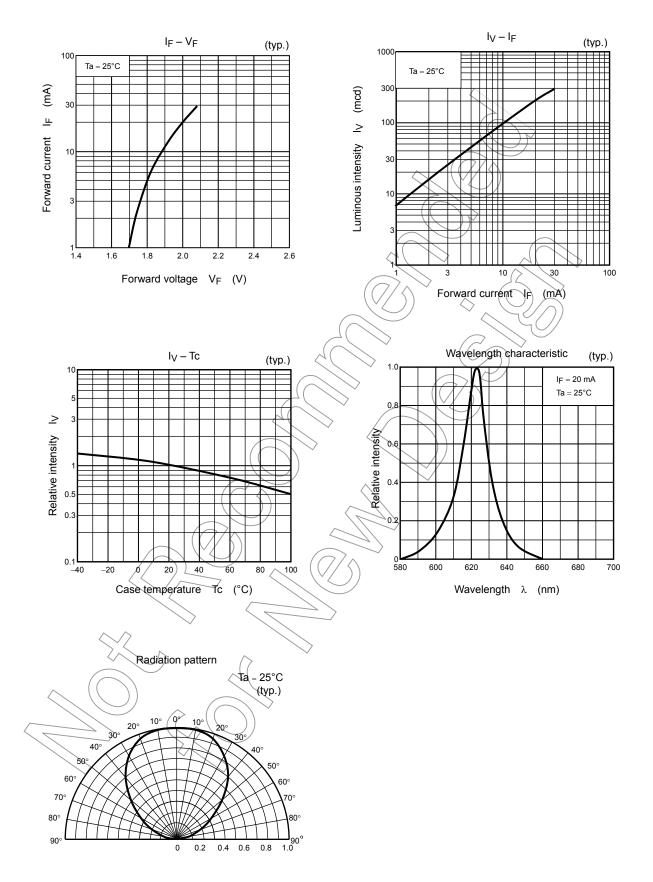
Cautions

- This visible LED lamp also emits some IR light.
- If a photodetector is located near the LED lamp, please ensure that it will not be affected by the IR light.
 This product is designed as a general display light source usage, and it has applied the measurement standard that matched with the sensitivity of human's eyes. Therefore, it is not intended for usage of functional application (ex. Light source for sensor, optical communication and etc) except general display light source.

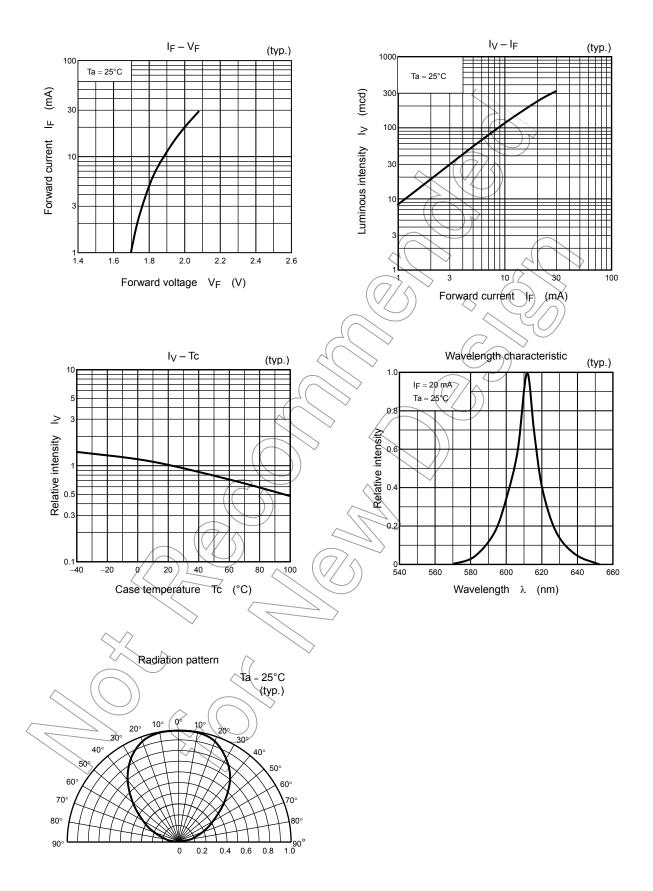
TLRF1060



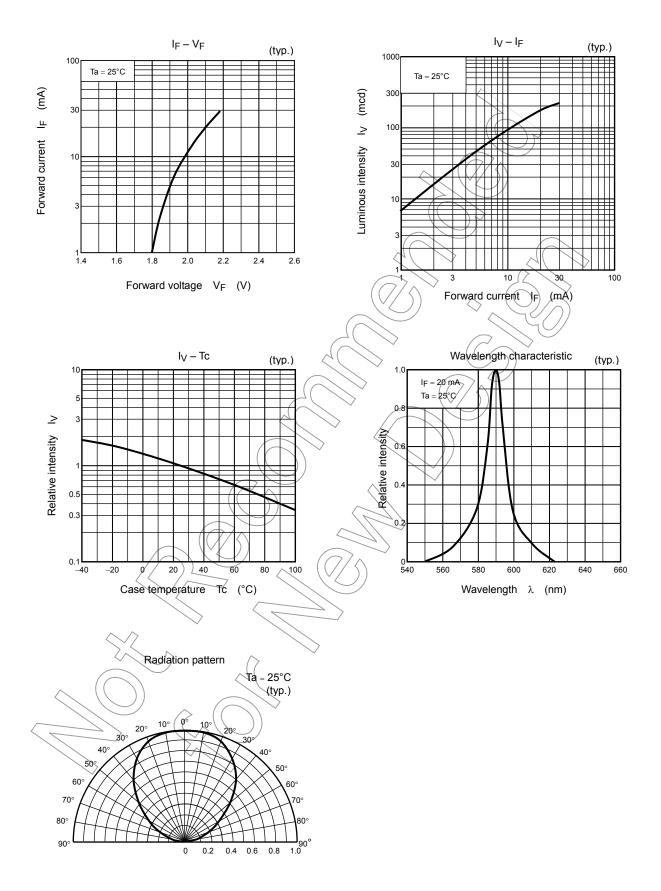
TLSF1060



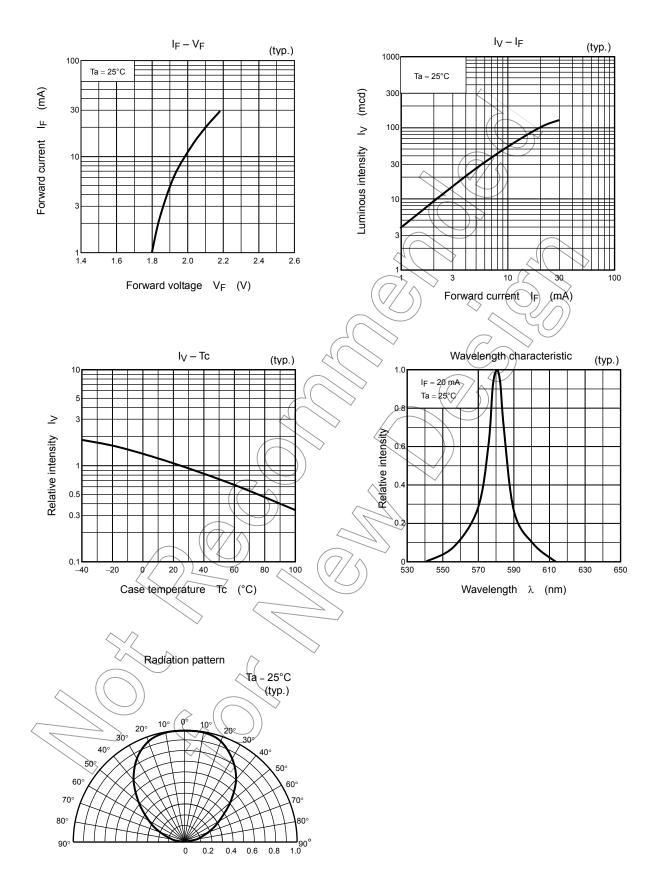
TLOF1060



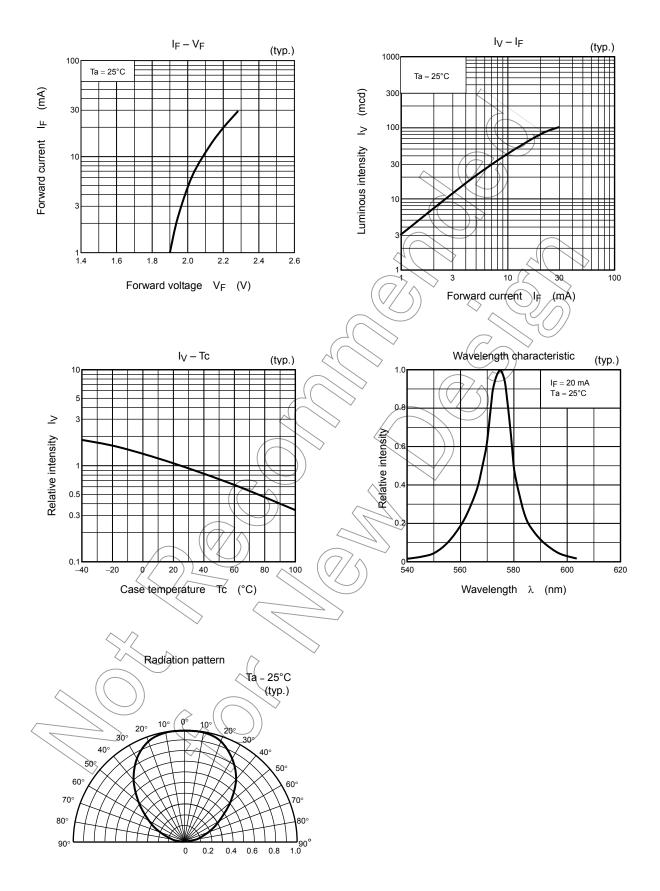
TLYF1060



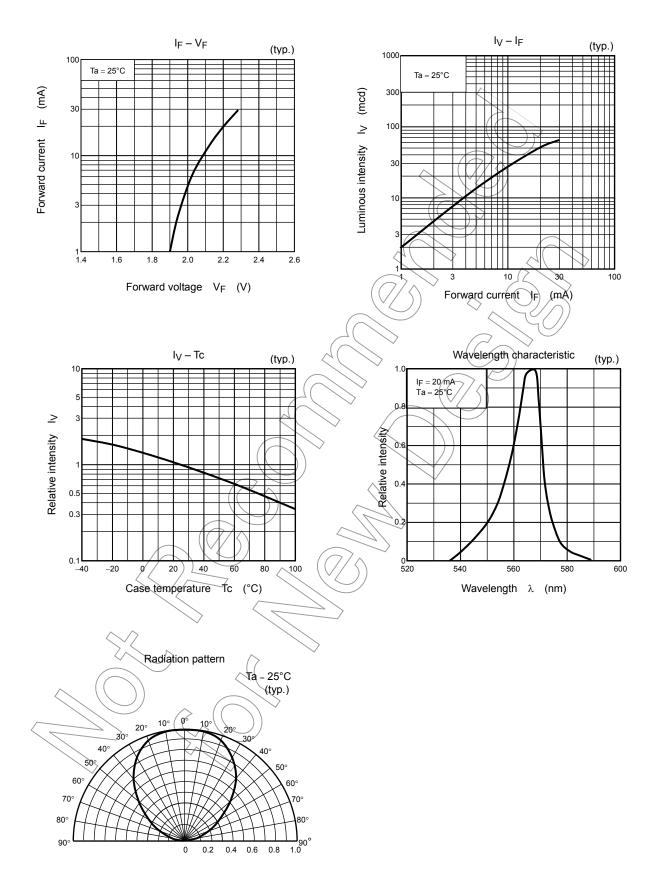
TLPYF1060



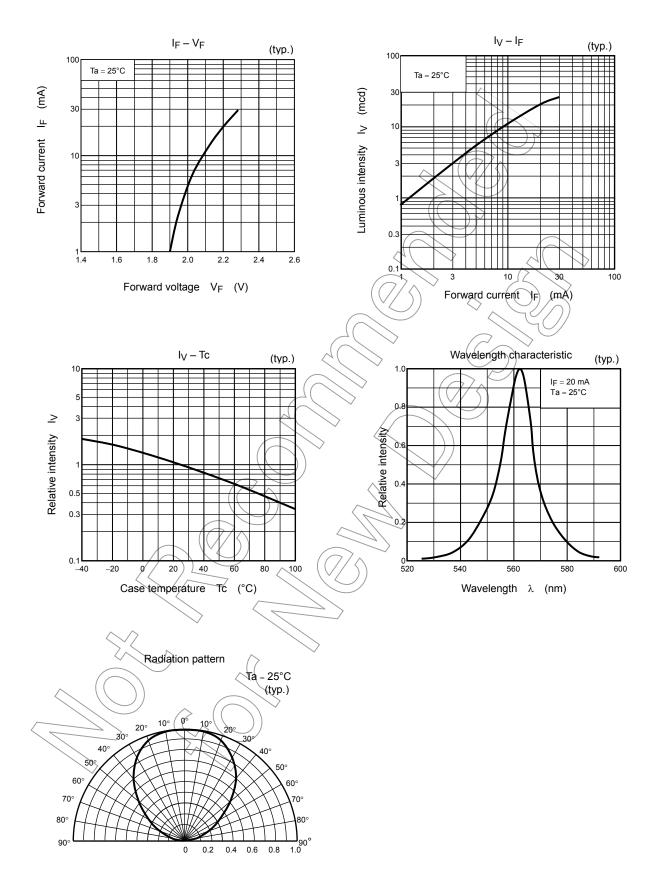
TLGF1060



TLFGF1060



TLPGF1060



Temperature profile for Pb-free soldering (example)

Packaging

These LED devices are packed in an aluminum envelope with a silica gel and a moisture indicator to avoid moisture absorption. The optical characteristics of the devices may be affected by exposure to moisture in the air before soldering and they should therefore be stored under the following conditions:

- This moisture proof bag may be stored unopened within 12 months at the following conditions. Temperature: 5°C to 30°C Humidity: 90% (max)
- 2. After opening the moisture proof bag, the devices should be assembled within 168 hours in an environment of 5°C to 30°C/60% RH or below.
- 3. If upon opening, the moisture indicator card shows humidity 30% or above (Color of indication changes to pink) or the expiration date has passed, the devices should be baked in taping with reel. After baking, use the baked devices within 72 hours, but perform baking only once. Baking conditions: 60±5°C, for 12 to 24 hours.

Expiration date: 12 months from sealing date, which is imprinted on the label.

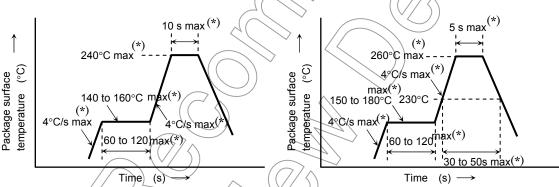
- 4. Repeated baking can cause the peeling strength of the taping to change, then leads to trouble in mounting. Furthermore, prevent the devices from being destructed against static electricity for baking of it.
- 5. If the packing material of laminate would be broken, the hermeticity would deteriorate. Therefore, do not throw or drop the packed devices.

Mounting Method

Soldering

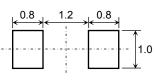
Reflow soldering

Temperature profile for Pb soldering (example)



- The products are evaluated using above reflow soldering conditions. No additional test is performed exceed the condition (i.e. the condition more than (*)MAX values) as a evaluation. Please perform reflow soldering under the above conditions.
- Please perform the first reflow soldering with reference to the above temperature profile and within 168 h of opening the package.
- Second reflow soldering In case of second reflow soldering should be performed within 168 h of the first reflow under the above conditions. Storage conditions before the second reflow soldering: 30°C, 60% RH (max)
- Make any necessary soldering corrections manually.
 - (only once at each soldering point) Soldering iron: 25 W Temperature: 300°C or less Time: within 3 s
- Do not perform wave soldering.

Recommended soldering pattern



Unit: mm



I Init: mm

Cleaning

When cleaning is required after soldering, Toshiba recommends the following cleaning solvents. It is confirmed that these solvents have no effect on semiconductor devices in our dipping test (under the recommended conditions). In selecting the one for your actual usage, please perform sufficient review on washing condition, using condition and etc.

ASAHI CLEAN AK-225AES: KAO CLEAN THROUGH 750H: PINE ALPHA ST-100S: (made by ASAHI GLASS) (made by KAO) (made by ARAKAWA CHEMICAL)

Precautions when Mounting

Do not apply force to the plastic part of the LED under high-temperature conditions. To avoid damaging the LED plastic, do not apply friction using a hard material. When installing the PCB in a product, ensure that the device does not come into contact with other emponents.

Tape Specifications

1. Product number format

The type of package used for shipment is denoted by a symbol suffix after the product number. The method of classification is as below. (this method, however does not apply to products whose electrical characteristics differ from standard Toshiba specifications)

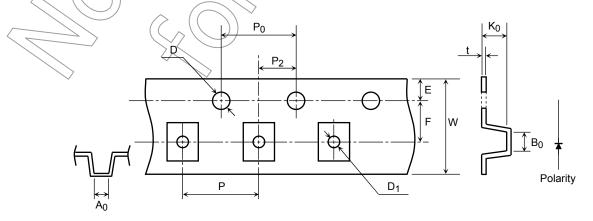
- (1) Tape Type: T18 (4-mm pitch)
- (2) Example

 TLSF1060
 (T18)

 Tape type

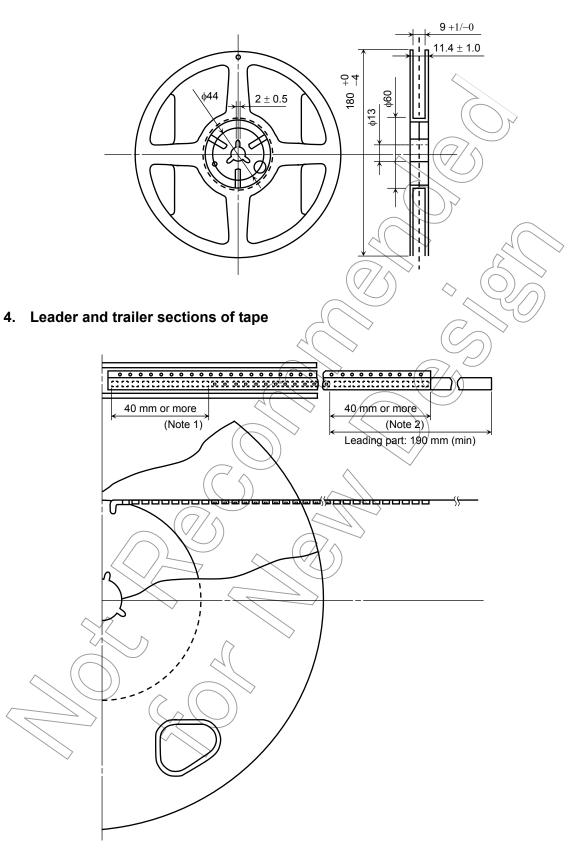
2. Tape dimensions

-		\sim	_	7/	$\langle \rangle$	Unit. min
Symbol	Dimension	Tolerance		Symbol	Dimension	Tolerance
D	(1.5)	+0.1/-0	\langle	(P_2)	2.0	±0.05
E	1.75	±0.1		W	8.0	±0.2
P ₀	4.0	±0.1		P	4.0	±0.1
t 🔨	0.2	±0.05		A ₀	1.5	±0.1
F	3,5	±0.05		∕ в₀	2.5	±0.1
D ₁	1.1	±0.1		K ₀	1.5	±0.1



3. Reel dimensions

Unit: mm



Note 1: Empty trailer section Note 2: Empty leader section

5. Packing display

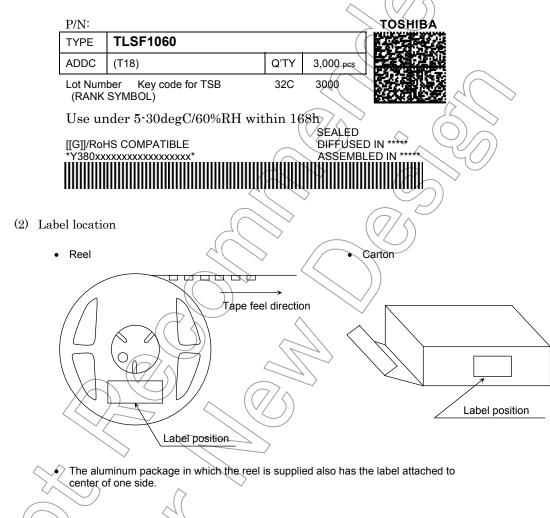
(1) Packing quantity

Reel	3,000 pcs
Carton	15,000 pcs

(2) Packing form: Each reel is sealed in an aluminum pack with silica gel.

6. Label format

(1) Example: TLSF1060 (T18)



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